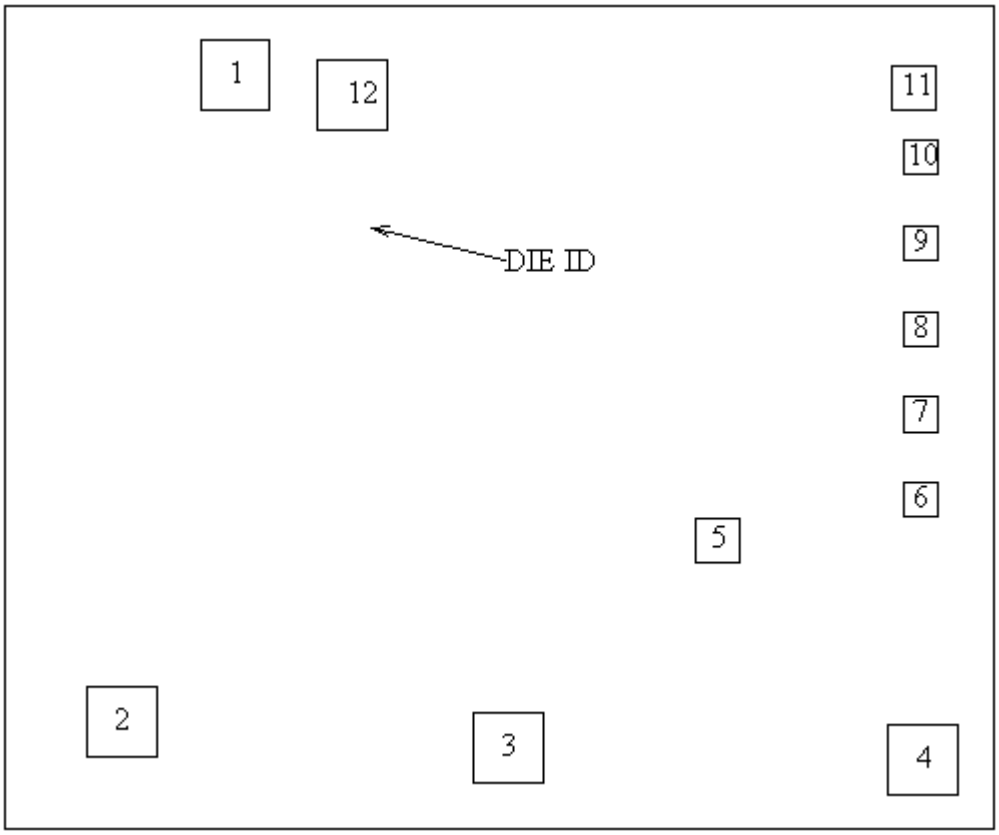
LM2937E-5.0 MDC MWC
500 MA LOW DROPOUT REGULATOR

February 28,2007

DIE LAYOUT (A -STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM2937	Bond Pad Opening Size (min)	161µm x 161µm
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	TI,NI,AG
Die Size (Drawn)	1905µm x 2286µm 75.0mils x 90.0mils	Back Side Connection	GND
Thickness	330µm Nominal		
Min Pitch	160µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
INPUT	1	-609	792	161	x	161
OUTPUT	2	-871	-704	161	x	161
OUTPUT	3	21	-764	161	x	161
GND	4	982	-792	161	x	161
NC	5	508	-285	102	x	102
NC	6	975	-191	80	x	80
NC	7	975	7	80	x	80
NC	8	975	204	80	x	80
NC	9	975	402	80	x	80
NC	10	975	601	80	x	80
NC	11	960	761	102	x	102
GND	12	-337	746	161	x	161

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